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09/705237

11/02/00

	Class	Subclass	ISSUE CLASSIFICATION

PATENT NUMBER

U.S. UTILITY Patent Application

O.I.P.E.	PATENT DATE
AK UT ² O.A. AG.	11/02/00

APPLICATION NO. 09/705237	CONT/PRIOR F	CLASS 264	SUBCLASS	ART UNIT 1732	EXAMINER Nguyen
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APPLICANTS

Michio Osada
Keiji Maeda
Yoshihisa Kawamoto
Yoshiji Shimizu

TITLE

Die used for resin-sealing and molding an electronic component

PTO-2040
12/99

ISSUING CLASSIFICATION

ORIGINAL		CROSS REFERENCE(S)					
CLASS	SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)				
INTERNATIONAL CLASSIFICATION							

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<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed. <input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____	_____ (Assistant Examiner) (Date)			NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	_____ (Primary Examiner) (Date)			ISSUE FEE	
				Amount Due	Date Paid
	_____ (Legal Instruments Examiner) (Date)			ISSUE BATCH NUMBER	

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